

## Dual N-Channel 20 V (D-S) MOSFET

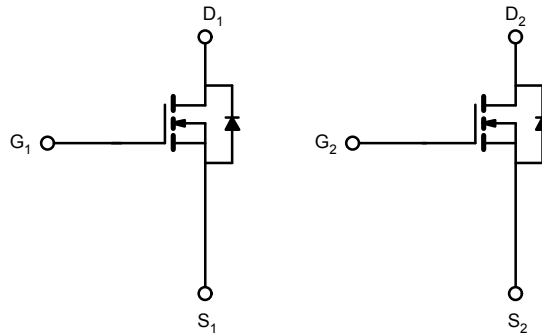
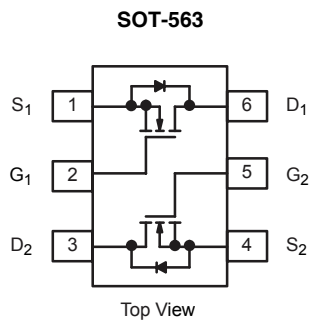
PRODUCT SUMMARY			
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)
20	0.310at V <sub>GS</sub> = 4.5 V	1.2 <sup>a</sup>	1.5 nC
	0.405at V <sub>GS</sub> = 2.5 V	0.5 <sup>a</sup>	

### FEATURES

- DT-Trench Power MOSFET
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC



**RoHS**  
COMPLIANT



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25 °C, unless otherwise noted)			
Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	20	V
Gate-Source Voltage	V <sub>GS</sub>	± 12	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	I <sub>D</sub>	T <sub>C</sub> = 25 °C	1.2 <sup>a</sup>
		T <sub>C</sub> = 70 °C	0.9 <sup>a</sup>
		T <sub>A</sub> = 25 °C	0.7 <sup>a, b, c</sup>
		T <sub>A</sub> = 70 °C	0.6 <sup>b, c</sup>
Pulsed Drain Current	I <sub>DM</sub>	3.5	A
Maximum Power Dissipation	P <sub>D</sub>	T <sub>C</sub> = 25 °C	1.0
		T <sub>C</sub> = 70 °C	0.8
		T <sub>A</sub> = 25 °C	0.74 <sup>b, c</sup>
		T <sub>A</sub> = 70 °C	0.47 <sup>b, c</sup>
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>b, d</sup>	R <sub>thJA</sub>	125	160	°C/W
Maximum Junction-to-Foot (Drain)	R <sub>thJF</sub>	70	95	

Notes:

- Package limited.
- Surface mounted on 1" x 1" FR4 board.
- t = 5 s.
- Maximum under steady state conditions is 220 °C/W.

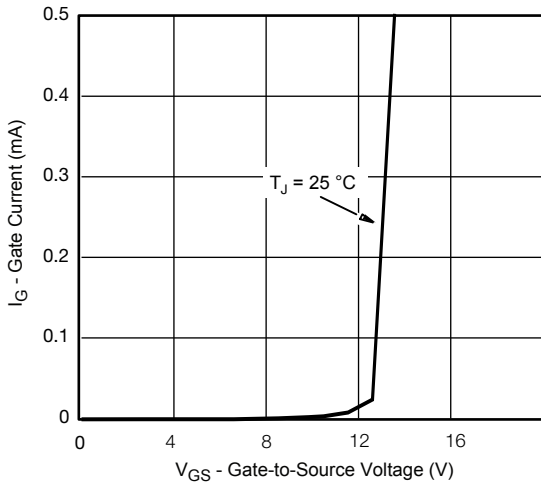
<b>SPECIFICATIONS</b> ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	20			V
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = 250\text{ }\mu\text{A}$		30		mV/ $^\circ\text{C}$
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$		-2.9			
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	0.4		1.2	V
Gate-Source Leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 12\text{ V}$			$\pm 100$	$\mu\text{A}$
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 16\text{ V}, V_{GS} = 0\text{ V}$			1	$\mu\text{A}$
		$V_{DS} = 16\text{ V}, V_{GS} = 0\text{ V}, T_J = 55\text{ }^\circ\text{C}$			10	
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$V_{DS} \leq 5\text{ V}, V_{GS} = 4.5\text{ V}$	3.5			A
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 0.8\text{ A}$		0.230	0.258	$\Omega$
		$V_{GS} = 4.5\text{ V}, I_D = 0.4\text{ A}$		0.310	0.350	
		$V_{GS} = 2.5\text{ V}, I_D = 0.3\text{ A}$		0.405	0.480	
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = 4\text{ V}, I_D = 0.5\text{ A}$		3.0		S
<b>Dynamic<sup>b</sup></b>						
Input Capacitance	$C_{ISS}$	$V_{DS} = -10\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$		40		pF
Output Capacitance	$C_{OSS}$			35		
Reverse Transfer Capacitance	$C_{RSS}$			28		
Total Gate Charge	$Q_g$	$V_{DS} = 10\text{ V}, V_{GS} = 10\text{ V}, I_D = 0.5\text{ A}$		1.5	2.0	nC
		$V_{DS} = 10\text{ V}, V_{GS} = 4.5\text{ V}, I_D = 0.5\text{ A}$		0.9	1.8	
Gate-Source Charge	$Q_{gs}$			0.1		
Gate-Drain Charge	$Q_{gd}$			0.2		
Gate Resistance	$R_g$	$f = 1\text{ MHz}$		2.6	3.8	$\Omega$
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 15\text{ V}, R_L = 15\text{ }\Omega$ $I_D \cong 0.5\text{ A}, V_{GEN} = 10\text{ V}, R_g = 6\text{ }\Omega$		10		ns
Rise Time	$t_r$			19		
Turn-Off Delay Time	$t_{d(off)}$			22		
Fall Time	$t_f$			8		
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Source-Drain Diode Current	$I_S$	$T_C = 25\text{ }^\circ\text{C}$			0.6	A
Pulse Diode Forward Current	$I_{SM}$				1.8	
Body Diode Voltage	$V_{SD}$	$I_S = 0.8\text{ A}, V_{GS} = 0\text{ V}$		0.8	1.2	V
Body Diode Reverse Recovery Time	$t_{rr}$	$I_F = 0.6\text{ A}, di/dt = 100\text{ A}/\mu\text{s}, T_J = 25\text{ }^\circ\text{C}$		6.1		ns
Body Diode Reverse Recovery Charge	$Q_{rr}$			1.5		nC

**Notes:**

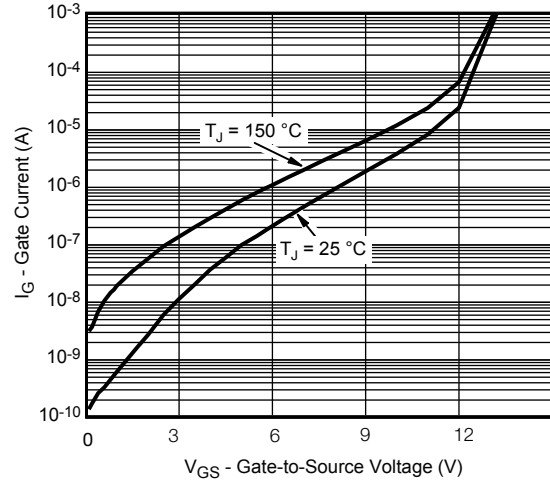
- a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .  
 b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

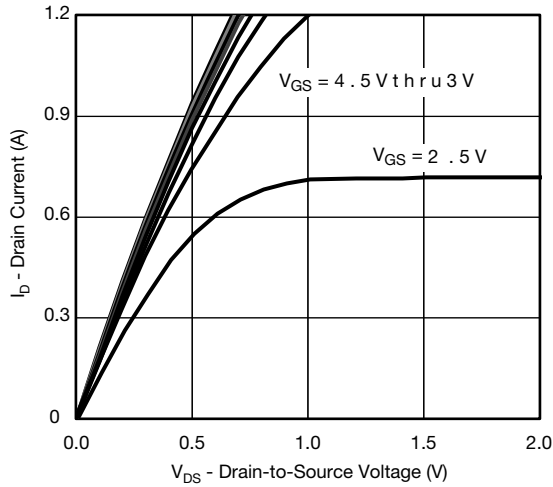
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



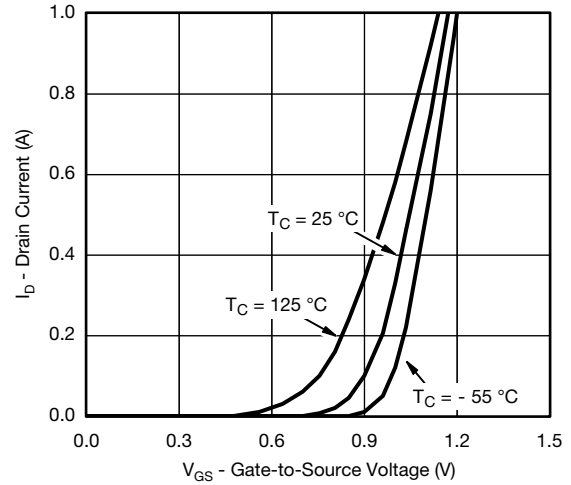
**Gate Current vs. Gate-to-Source Voltage**



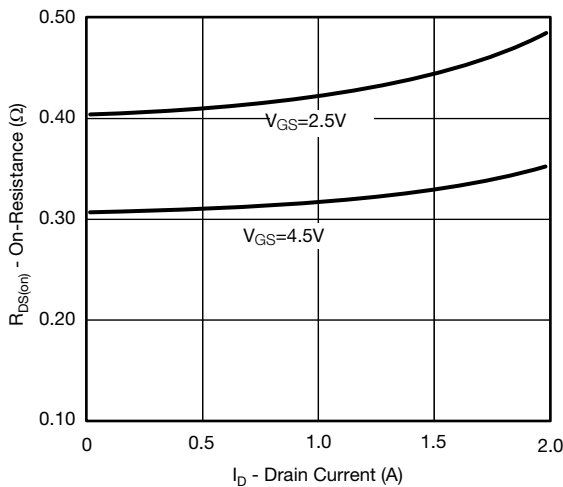
**Gate Current vs. Gate-to-Source Voltage**



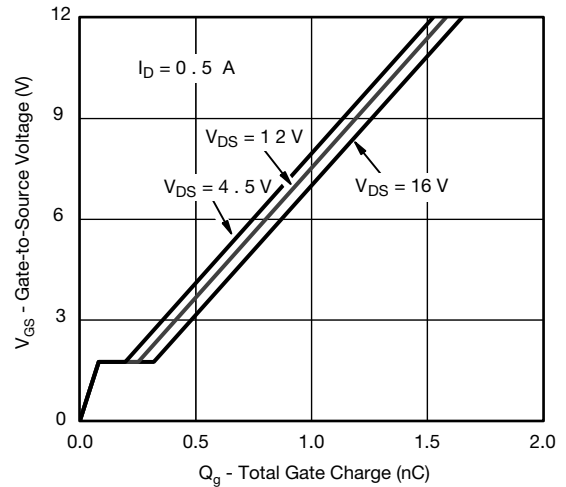
**Output Characteristics**



**Transfer Characteristics**

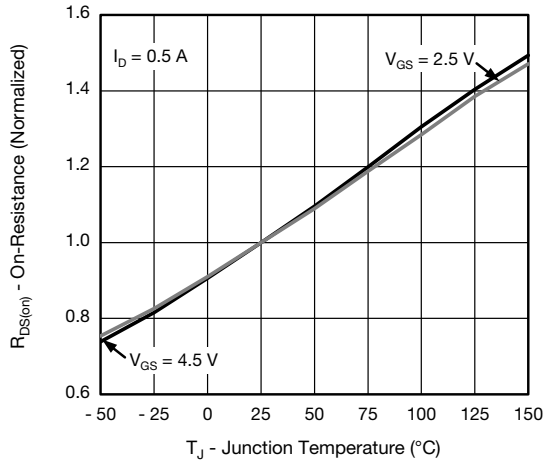


**On-Resistance vs. Drain Current**

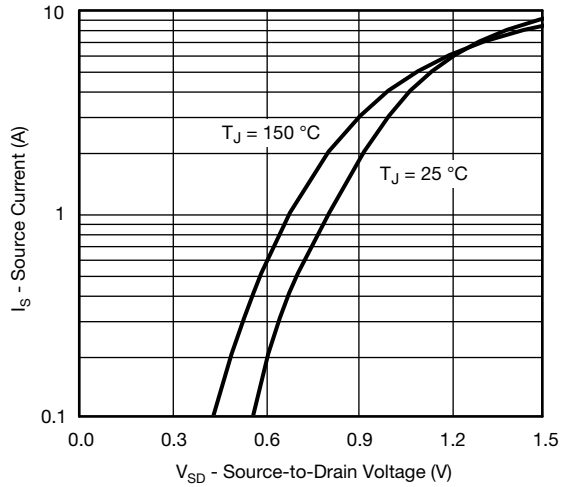


**Gate Charge**

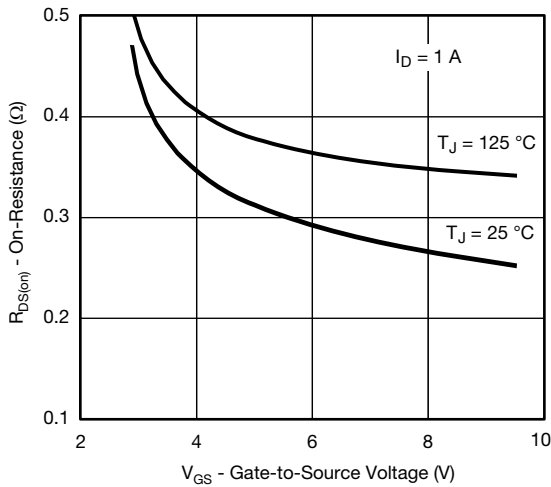
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



**On-Resistance vs. Junction Temperature**



**Source-Drain Diode Forward Voltage**



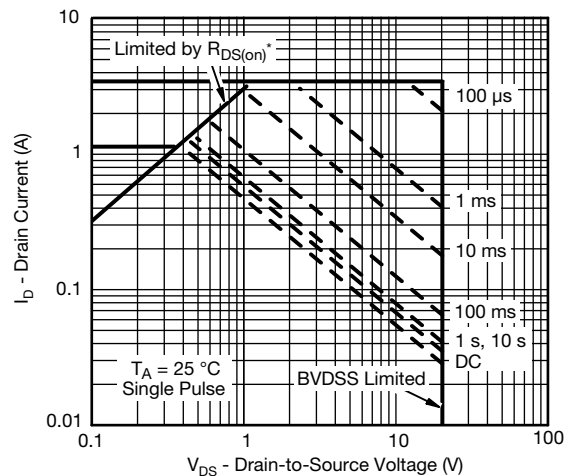
**On-Resistance vs. Gate-to-Source Voltage**



**Threshold Voltage**

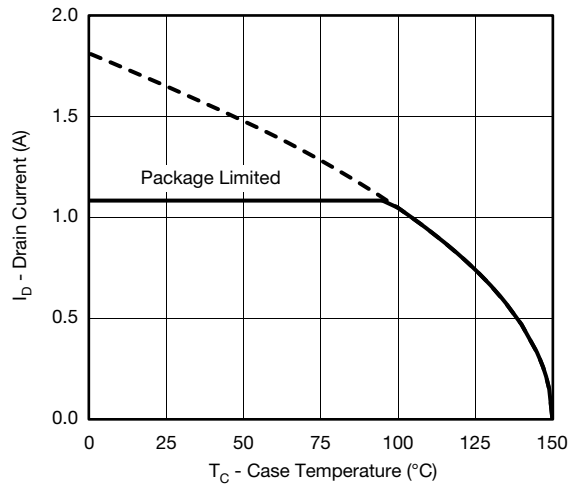


**Single Pulse Power, Junction-to-Ambient**

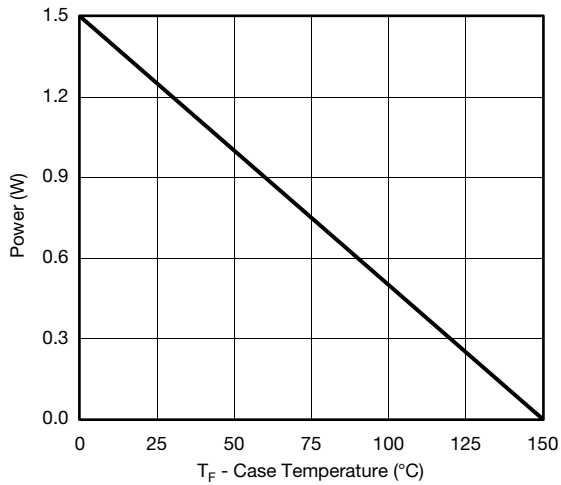


**Safe Operating Area, Junction-to-Ambient**  
\*  $V_{GS} >$  minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

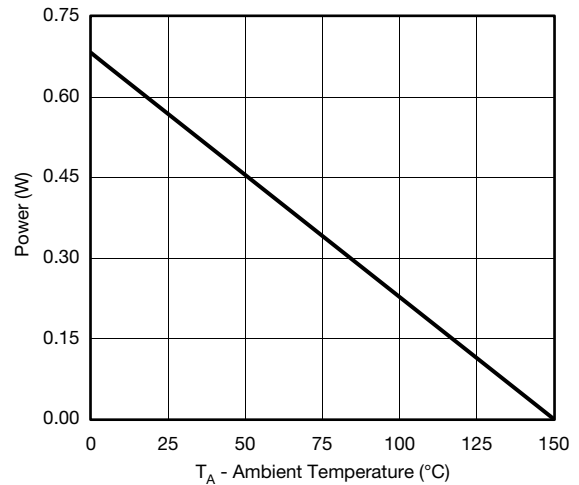
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



**Current Derating\***



**Power, Junction-to-Foot**



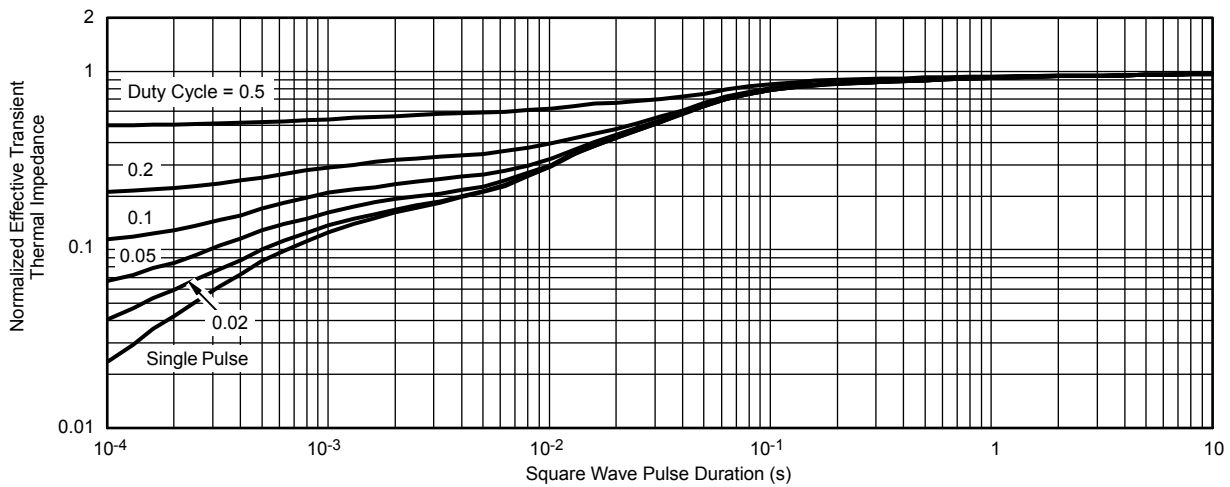
**Power, Junction-to-Ambient**

\* The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

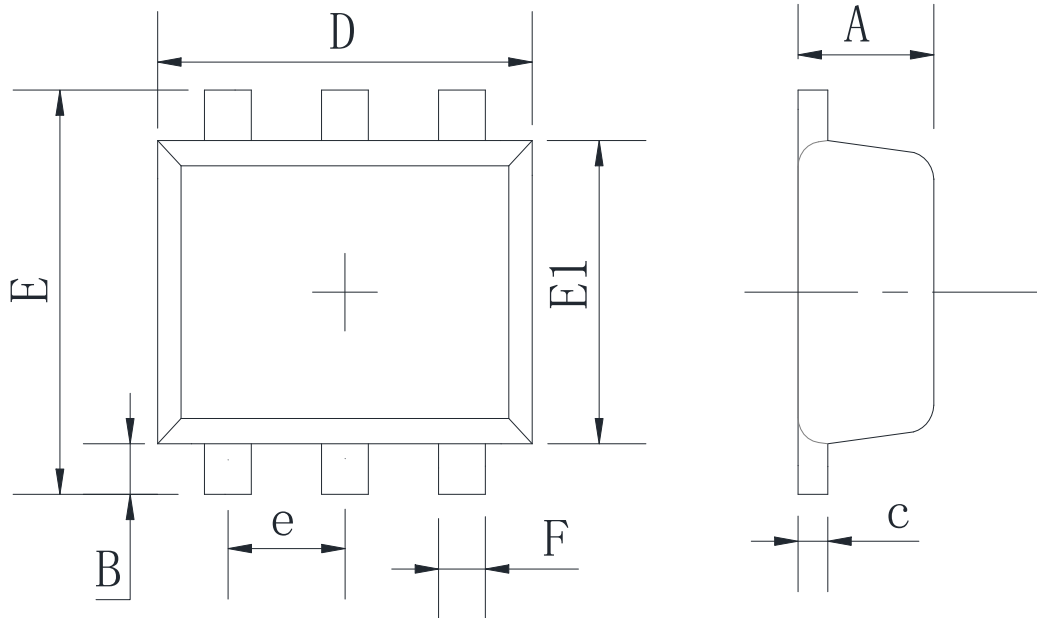


**Normalized Thermal Transient Impedance, Junction-to-Ambient**



**Normalized Thermal Transient Impedance, Junction-to-Foot**

SOT-563 PACKAGE OUTLINE



COMMON DIMENSIONS  
(UNITS OF MEASURE=MILLIMETER)

Symbol	Min	Typ	Max
A	0.53	0.58	0.63
B	0.15	0.20	0.25
c	0.10	0.127	0.16
D	1.50	1.55	1.65
E	1.50	1.60	1.70
E1	1.10	1.20	1.30
e	0.40	0.50	0.60
F	0.15	0.20	0.25

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